

L Number	Hits	Search Text	DB	Time stamp
1	673442	nozzle nozzles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:39
2	226181	nozzles	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:39
3	959858	bar manifold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:39
4	10735	nozzles with (bar manifold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
5	34038	supply adj lines	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:40
6	82334	slurry with water	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
7	82595	slurry with (water diluting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:40
8	0	((nozzles with (bar manifold)) same (supply adj lines) same (slurry with (water diluting)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:40
9	89	((nozzles with (bar manifold)) same (supply adj lines))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:40
10	2	((nozzles with (bar manifold)) same (supply adj lines)) and (slurry with (water diluting))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
11	2	((nozzles with (bar manifold)) same (supply adj lines)) and (slurry with water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
12	253313	slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
13	4	((nozzles with (bar manifold)) same (supply adj lines)) and slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:41
14	15542	nozzles same (bar manifold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:42

15	150	(nozzles same (bar manifold)) same (supply adj lines)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:43
16	1	((nozzles same (bar manifold)) same (supply adj lines)) same slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:42
17	88	(nozzles same (bar manifold)) same (slurry with (water diluting))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:43
18	370252	wafer wafers	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:43
19	2	((nozzles same (bar manifold)) same (slurry with (water diluting))) and (wafer wafers)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 07:44
20	822	451/60	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 08:13
21	310	(colloidal adj (alumina silica)) with (deionized adj water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 08:14
22	9	451/60 and ((colloidal adj (alumina silica)) with (deionized adj water))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/04 08:14